

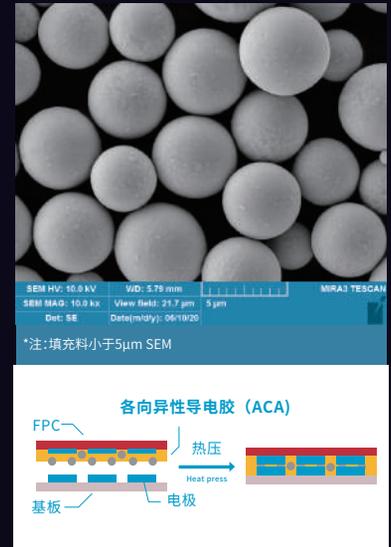
# 各向异性导电胶

## Anisotropic Conductive Adhesive

# FACA-138

FACA-138 系列是我司自主研发、生产的低温（填充料熔点 138°C）冶金连接各向异性导电胶，采用专利技术的超窄粒径超微焊锡粉与胶黏剂相结合，实现只在单一方向（垂直面）导电，而在另一方（水平面）不导电（绝缘电阻  $1 \times 10^9 \Omega$ ）的特殊导电胶。同时可满足印刷（FACA-138P 系列）与点胶（FACA-138D 系列）的生产工艺要求。

FACA-138 series is a low-temperature (filler melting point 138°C) metallurgical connection anisotropic conductive adhesive independently developed and produced by our company. It uses patented technology to combine ultra-narrow particle size and ultra-fine solder powder with adhesives to achieve A special conductive adhesive that conducts electricity in a single direction (vertical plane), but does not conduct electricity on the other side (horizontal plane) (insulation resistance  $1 \times 10^9 \Omega$ ). At the same time, it can meet the production process requirements of printing (FACA-138P series) and dispensing (FACA-138D series).



## 特性 Features



### 垂直导电，水平不导电

Vertically conductive, horizontally non-conductive



### 印刷、点胶流畅，不粘网不堵孔

Good printing and dispensing, non-sticking nets and non-blocking holes



### 窄间距（小于20或10μm）连接，低温冶金焊接

Narrow pitch (less than 20 or 10μm) connection, low melting point metallurgical welding



### 导电填充料粒度均匀及产品分散性好，热固化后绝缘材料粘结增加可靠性

The conductive filler has uniform particle size and good product dispersion. After thermal curing, the bonding of insulating materials increases reliability



### 热压温度较低，粘接强度高，零卤素

Low hot pressing temperature, high bonding strength, zero halogen



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## 性能参数 Parameter

产品名称 Product	FACA-1389P	FACA-138XP	FACA-1389D	FACA-138XD
锡粉尺寸 Size	T9 1-5 $\mu$ m	T10 1-3 $\mu$ m	T9 1-5 $\mu$ m	T10 1-3 $\mu$ m
D50	3.3 $\mu$ m	2.0 $\mu$ m	3.3 $\mu$ m	2.0 $\mu$ m
涂覆方法 Using method	印刷 printing	印刷 printing	点胶或针转移 Dispensing, Pin transfer	点胶或针转移 Dispensing, Pin transfer
产品包装 Packaging	罐装/Canned 100g, 200g, 500g		针筒装/Syringe 10g, 20g, 30g	
合金组成 Alloy	Sn42Bi57.6Ag0.4	Sn42Bi57.6Ag0.4	Sn42Bi57.6Ag0.4	Sn42Bi57.6Ag0.4
熔点 Melting point	138 $^{\circ}$ C	138 $^{\circ}$ C	138 $^{\circ}$ C	138 $^{\circ}$ C
固化温度 curing Temp	150 $^{\circ}$ C & 1Mpa @30~60sec	150 $^{\circ}$ C & 1Mpa @30~60sec	150 $^{\circ}$ C & 1Mpa @30~60sec	150 $^{\circ}$ C & 1Mpa @30~60sec
粘度 Pa.s	40~80	40~80	20~50	20~50
Ti值	0.3~0.7	0.3~0.7	0.3~0.6	0.3~0.6
合金比例 Alloy %	5~20%	5~20%	5~20%	5~20%
胶黏剂比例 Flux %	80~95%	80~95%	80~95%	80~95%
残留物干燥度 Residue dryness	Pass JIS Z 3284	Pass JIS Z 3284	Pass JIS Z 3284	Pass JIS Z 3284
卤素含量 Halogen content	零卤素 氯元素或溴元素小于50 ppm, 总量小于100 ppm Zero halogen Cl or Br <50 ppm, total <100 ppm			

\*可按客户需求进行产品的粒度、粘度、特殊应用进行定制。 Can be customized the particle size, viscosity and product special applications.

## 产品应用

### Product Application

电子元件制造过程中在两个窄间距导电连接点的焊接使用，避免产生线路间的短路，提高良率。应用在触摸屏、智能卡、射频识别（RFID）、倒装芯片（Flip chip）、FPC等产品。适合于微电子超细间距线路的组装与封装领域，更有利于微电子封装的微型化。

The welding of two narrow-pitch conductive connection points in the manufacturing process of electronic components can avoid short circuits between circuits and improve yield. Used in touch screens, smart cards, radio frequency identification, flip chip, FPC and other products. It is suitable for the assembly and packaging of micro-electronic ultra-narrow pitch circuits, and is more conducive to the miniaturization of microelectronic packaging.

## 注意事项 Precautions

### 01 热压条件 /Hot pressing temperature

热压温度高于熔点（138 $^{\circ}$ C）的温度 10~30 $^{\circ}$ C，压力 1 Mpa 时间 30~60 秒。

The hot pressing temperature is higher than the melting point (138 $^{\circ}$ C) by 10~30 $^{\circ}$ C & 1Mpa @ 30~60sec

### 02 产品储存 /Product storage

冷冻储存在 -20 $^{\circ}$ C 的条件

Store at -20 $^{\circ}$ C